



Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	1232
Number of Logic Elements/Cells	11088
Total RAM Bits	811008
Number of I/O	396
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FCBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp7-6ff896c

Disparity Control

The 8B/10B encoder is initialized with a negative running disparity. Unique control allows forcing the current running disparity state.

TXRUNDISP signals its current running disparity. This may be useful in those cases where there is a need to manipulate the initial running disparity value.

Bits TXCHARDISPMODE and TXCHARDISPVAL control the generation of running disparity before each byte.

For example, the transceiver can generate the sequence

```
K28.5+ K28.5+ K28.5- K28.5-
or
K28.5- K28.5- K28.5+ K28.5+
```

by specifying inverted running disparity for the second and fourth bytes.

Transmit FIFO

Proper operation of the circuit is only possible if the FPGA clock (TXUSRCLK) is frequency-locked to the reference clock (REFCLK). Phase variations up to one clock cycle are allowable. The FIFO has a depth of four. Overflow or underflow conditions are detected and signaled at the interface. Bypassing of this FIFO is programmable.

8B/10B Encoder

Note: In the RocketIO transceiver, the most-significant byte is sent first; in the RocketIO X transceiver, the least-significant byte is sent first.

A bypassable 8B/10B encoder is included. The encoder uses the same 256 data characters and 12 control characters used by Gigabit Ethernet, Fibre Channel, and InfiniBand.

The encoder accepts 8 bits of data along with a K-character signal for a total of 9 bits per character applied, and generates a 10 bit character for transmission. If the K-character signal is High, the data is encoded into one of the twelve possible K-characters available in the 8B/10B code. If the K-character input is Low, the 8 bits are encoded as standard data. If the K-character input is High, and a user applies other than one of the twelve possible combinations, TXKERR indicates the error.

8B/10B Decoder

Note: In the RocketIO transceiver, the most-significant byte is sent first; in the RocketIO X transceiver, the least-significant byte is sent first.

An optional 8B/10B decoder is included. A programmable option allows the decoder to be bypassed. When the 8B/10B decoder is bypassed, the 10-bit character order is, for example,

```
RXCHARISK[0]          (first bit received)
RXRUNDISP[0]
RXDATA[7:0]           (last bit received is RXDATA[0])
```

The decoder uses the same table that is used for Gigabit Ethernet, Fibre Channel, and InfiniBand. In addition to

decoding all data and K-characters, the decoder has several extra features. The decoder separately detects both "disparity errors" and "out-of-band" errors. A disparity error is the reception of 10-bit character that exists within the 8B/10B table but has an incorrect disparity. An out-of-band error is the reception of a 10-bit character that does not exist within the 8B/10B table. It is possible to obtain an out-of-band error without having a disparity error. The proper disparity is always computed for both legal and illegal characters. The current running disparity is available at the RXRUNDISP signal.

The 8B/10B decoder performs a unique operation if out-of-band data is detected. If out-of-band data is detected, the decoder signals the error and passes the illegal 10-bits through and places them on the outputs. This can be used for debugging purposes if desired.

The decoder also signals the reception of one of the 12 valid K-characters. In addition, a programmable comma detect is included. The comma detect signal registers a comma on the receipt of any comma+, comma-, or both. Since the comma is defined as a 7-bit character, this includes several out-of-band characters. Another option allows the decoder to detect only the three defined commas (K28.1, K28.5, and K28.7) as comma+, comma-, or both. In total, there are six possible options, three for valid commas and three for "any comma."

Note that all bytes (1, 2, 4, or 8) at the RX FPGA interface each have their own individual 8B/10B indicators (K-character, disparity error, out-of-band error, current running disparity, and comma detect).

Receiver Buffer

The receiver includes buffers (FIFOs) in the datapath. This section gives the reasons for including the buffers and outlines their operation.

The receiver buffer is required for two reasons:

- *Clock correction* to accommodate the slight difference in frequency between the recovered clock RXRECCLK and the internal FPGA user clock RXUSRCLK
- *Channel bonding* to allow realignment of the input stream to ensure proper alignment of data being read through multiple transceivers

The receiver uses an *elastic buffer*, where "elastic" refers to the ability to modify the read pointer for clock correction and channel bonding.

Comma Detection

Word alignment is dependent on the state of comma detect bits. If comma detect is enabled, the transceiver recognizes up to two 10-bit preprogrammed characters. Upon detection of the character or characters, the comma detect output is driven high and the data is synchronously aligned. If a comma is detected and the data is aligned, no further alignment alteration takes place. If a comma is received and realignment is necessary, the data is realigned and an indi-

Other RocketIO X Features and Notes

Loopback

In order to facilitate testing without having the need to either apply patterns or measure data at GHz rates, four programmable loop-back features are available.

The first option, serial loopback, is available in two modes: *pre-driver* and *post-driver*.

- The pre-driver mode loops back to the receiver without going through the output driver. In this mode, TXP and TXN are not driven and therefore need not be terminated.
- The post-driver mode is the same as the RocketIO loopback. In this mode, TXP and TXN are driven and must be properly terminated.

The third option, parallel loopback, checks the digital circuitry. When parallel loopback is enabled, the serial loopback path is disabled. However, the transmitter outputs remain active, and data can be transmitted. If TXINHIBIT is asserted, TXP is forced to 0 until TXINHIBIT is de-asserted.

The fourth option, repeater loopback, allows received data to be transmitted without going through the FPGA fabric.

Reset

The receiver and transmitter have their own synchronous reset inputs. The transmitter reset, TXRESET, recenters the transmission FIFO and resets all transmitter registers and the encoder. The receiver reset, RXRESET, recenters the

receiver elastic buffer and resets all receiver registers and the decoder. When the signals TXRESET or RXRESET are asserted High, the PCS is in reset. After TXRESET or RXRESET are deasserted, the PCS takes five clocks to come out of reset for each clock domain.

The PMA configuration vector is not affected during this reset, so the PMA speed, filter settings, and so on, all remain the same. Also, the PMA internal pipeline is not affected and continues to operate in normal fashion.

Power

The transceiver voltage regulator circuits must not be shared with any other supplies (including FPGA supplies V_{CCINT} , V_{CCO} , V_{CCAUX} , and V_{REF}). Voltage regulators can be shared among transceiver power supplies of the same voltage, but each supply pin must still have its own separate passive filtering network.

All RocketIO transceivers in the FPGA, whether instantiated in the design or not, must be connected to power and ground. Unused transceivers can be powered by any 1.5V or 2.5V source, and passive filtering is not required.

The Power Down feature is controlled by the transceiver's POWERDOWN input pin. Any given transceiver that is not instantiated in the design is automatically set to the POWERDOWN state by the Xilinx ISE development software. The Power Down pin on the FPGA package has no effect on the MGT.

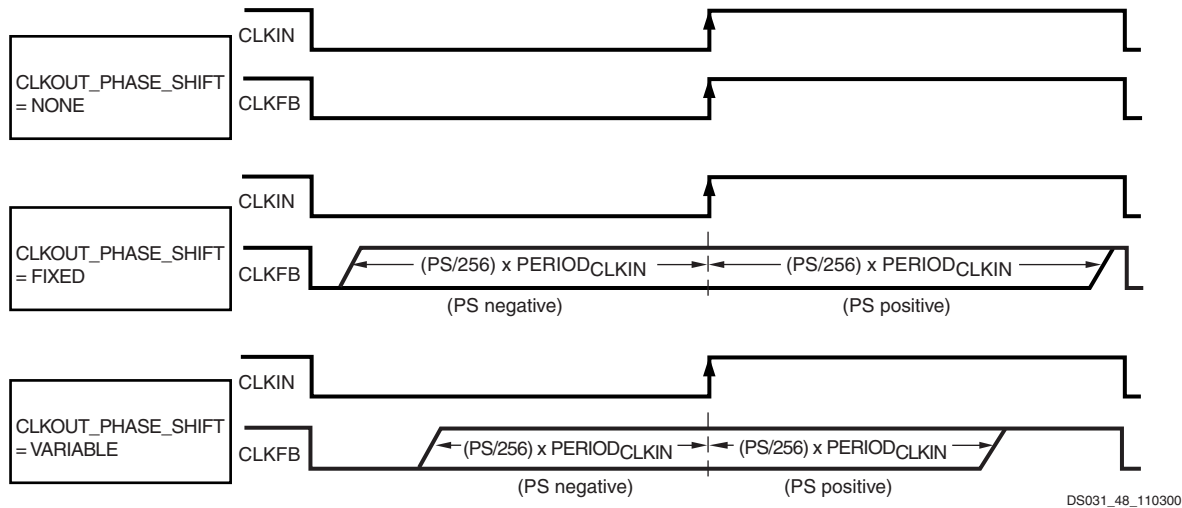


Figure 63: Fine-Phase Shifting Effects

Two separate components of the phase shift range must be understood:

- PHASE_SHIFT attribute range
- FINE_SHIFT_RANGE DCM timing parameter range

The PHASE_SHIFT attribute is the numerator in the following equation:

$$\text{Phase Shift (ns)} = (\text{PHASE_SHIFT}/256) * \text{PERIOD}_{\text{CLKIN}}$$

The full range of this attribute is always -255 to +255, but its practical range varies with CLKIN frequency, as constrained by the FINE_SHIFT_RANGE component, which represents the total delay achievable by the phase shift delay line. Total delay is a function of the number of delay taps used in the circuit. Across process, voltage, and temperature, this absolute range is guaranteed to be as specified under **DCM Timing Parameters** in *Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics*.

Absolute range (fixed mode) = $\pm \text{FINE_SHIFT_RANGE}$

Absolute range (variable mode) = $\pm \text{FINE_SHIFT_RANGE}/2$

The reason for the difference between fixed and variable modes is as follows. For variable mode to allow symmetric, dynamic sweeps from -255/256 to +255/256, the DCM sets the "zero phase skew" point as the middle of the delay line, thus dividing the total delay line range in half. In fixed mode,

since the PHASE_SHIFT value never changes after configuration, the entire delay line is available for insertion into either the CLKIN or CLKFB path (to create either positive or negative skew).

Taking both of these components into consideration, the following are some usage examples:

- If $\text{PERIOD}_{\text{CLKIN}} = 2 * \text{FINE_SHIFT_RANGE}$, then PHASE_SHIFT in fixed mode is limited to ± 128 , and in variable mode it is limited to ± 64 .
- If $\text{PERIOD}_{\text{CLKIN}} = \text{FINE_SHIFT_RANGE}$, then PHASE_SHIFT in fixed mode is limited to ± 255 , and in variable mode it is limited to ± 128 .
- If $\text{PERIOD}_{\text{CLKIN}} \leq 0.5 * \text{FINE_SHIFT_RANGE}$, then PHASE_SHIFT is limited to ± 255 in either mode.

Operating Modes

The frequency ranges of DCM input and output clocks depend on the operating mode specified, either low-frequency mode or high-frequency mode, according to **Table 30**. For actual values, see *Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics*. The CLK2X, CLK2X180, CLK90, and CLK270 outputs are not available in high-frequency mode.

High or low-frequency mode is selected by an attribute.

Table 30: DCM Frequency Ranges

Output Clock	Low-Frequency Mode		High-Frequency Mode	
	CLKIN Input	CLK Output	CLKIN Input	CLK Output
CLK0, CLK180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_1X_HF
CLK90, CLK270	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	NA	NA
CLK2X, CLK2X180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_2X_LF	NA	NA
CLKDV	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_DV_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_DV_HF
CLKFX, CLKFX180	CLKIN_FREQ_FX_LF	CLKOUT_FREQ_FX_LF	CLKIN_FREQ_FX_HF	CLKOUT_FREQ_FX_HF

Configuration

Virtex-II Pro devices are configured by loading application specific configuration data into the internal configuration memory. Configuration is carried out using a subset of the device pins, some of which are dedicated, while others can be re-used as general purpose inputs and outputs once configuration is complete.

Depending on the system design, several configuration modes are supported, selectable via mode pins. The mode pins M2, M1, and M0 are dedicated pins. The M2, M1, and M0 mode pins should be set at a constant DC voltage level, either through pull-up or pull-down resistors, or tied directly to ground or V_{CCAUX} . The mode pins should not be toggled during and after configuration.

An additional pin, HSWAP_EN is used in conjunction with the mode pins to select whether user I/O pins have pull-ups during configuration. By default, HSWAP_EN is tied High (internal pull-up) which shuts off the pull-ups on the user I/O pins during configuration. When HSWAP_EN is tied Low, user I/Os have pull-ups during configuration. Other dedicated pins are CCLK (the configuration clock pin), DONE, PROG_B, and the Boundary-Scan pins: TDI, TDO, TMS, and TCK. (The TDO pin is open-drain and does not have an internal pull-up resistor.) Depending on the configuration mode chosen, CCLK can be an output generated by the FPGA, or an input accepting an externally generated clock. The configuration pins and Boundary-Scan pins are independent of the V_{CCO} . The auxiliary power supply (V_{CCAUX}) of 2.5V is used for these pins. All configuration pins are LVCMOS25 12mA. See [Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics](#).

A "persist" option is available which can be used to force the configuration pins to retain their configuration function even after device configuration is complete. If the persist option is not selected then the configuration pins with the exception of CCLK, PROG_B, and DONE can be used as user I/O in normal operation. The persist option does not apply to the Boundary-Scan related pins. The persist feature is valuable in applications which employ partial reconfiguration or reconfiguration on the fly.

Configuration Modes

Virtex-II Pro supports the following five configuration modes:

- [Slave-Serial Mode](#)
- [Master-Serial Mode](#)
- [Slave SelectMAP Mode](#)
- [Master SelectMAP Mode](#)
- [Boundary-Scan \(JTAG, IEEE 1532\) Mode](#)

Refer to [Table 32, page 57](#).

A detailed description of configuration modes is provided in the *Virtex-II Pro Platform FPGA User Guide*.

Slave-Serial Mode

In slave-serial mode, the FPGA receives configuration data in bit-serial form from a serial PROM or other serial source of configuration data. The CCLK pin on the FPGA is an input in this mode. The serial bitstream must be setup at the DIN input pin a short time before each rising edge of the externally generated CCLK.

Multiple FPGAs can be daisy-chained for configuration from a single source. After a particular FPGA has been configured, the data for the next device is routed internally to the DOUT pin. The data on the DOUT pin changes on the falling edge of CCLK.

Slave-serial mode is selected by applying [111] to the mode pins (M2, M1, M0). A weak pull-up on the mode pins makes slave serial the default mode if the pins are left unconnected.

Master-Serial Mode

In master-serial mode, the CCLK pin is an output pin. It is the Virtex-II Pro FPGA device that drives the configuration clock on the CCLK pin to a Xilinx Serial PROM which in turn feeds bit-serial data to the DIN input. The FPGA accepts this data on each rising CCLK edge. After the FPGA has been loaded, the data for the next device in a daisy-chain is presented on the DOUT pin after the falling CCLK edge.

The interface is identical to slave serial except that an internal oscillator is used to generate the configuration clock (CCLK). A wide range of frequencies can be selected for CCLK which always starts at a slow default frequency. Configuration bits then switch CCLK to a higher frequency for the remainder of the configuration.

Slave SelectMAP Mode

The SelectMAP mode is the fastest configuration option. Byte-wide data is written into the Virtex-II Pro FPGA device with a BUSY flag controlling the flow of data. An external data source provides a byte stream, CCLK, an active Low Chip Select (CS_B) signal and a Write signal (RDWR_B). If BUSY is asserted (High) by the FPGA, the data must be held until BUSY goes Low. Data can also be read using the SelectMAP mode. If RDWR_B is asserted, configuration data is read out of the FPGA as part of a readback operation.

After configuration, the pins of the SelectMAP port can be used as additional user I/O. Alternatively, the port can be retained to permit high-speed 8-bit readback using the persist option.

Multiple Virtex-II Pro FPGAs can be configured using the SelectMAP mode, and be made to start-up simultaneously. To configure multiple devices in this way, wire the individual CCLK, Data, RDWR_B, and BUSY pins of all the devices in parallel. The individual devices are loaded separately by deasserting the CS_B pin of each device in turn and writing the appropriate data.

Table 19: Processor Block JTAG Switching Characteristics

		Speed Grade			
Description	Symbol	-7	-6	-5	Units
Setup and Hold Relative to Clock (JTAGC405TCK)					
JTAG control inputs	T _{PCKK_JTAG} / T _{PCKC_JTAG}	0.80/ 0.70	0.80/ 0.70	0.88/ 0.77	ns, min
JTAG reset input	T _{PCKK_JTAGRST} / T _{PCKC_JTAGRST}	0.80/ 0.70	0.80/ 0.70	0.88/ 0.77	ns, min
Clock to Out					
JTAG control outputs	T _{PCKCO_JTAG}	1.34	1.54	1.69	ns, max

Table 20: PowerPC 405 Data-Side On-Chip Memory Switching Characteristics

		Speed Grade			
Description	Symbol	-7	-6	-5	Units
Setup and Hold Relative to Clock (BRAMDSOCCLK)					
Data-Side On-Chip Memory data bus inputs	T _{PDCK_DSOCM} / T _{PCKD_DSOCM}	0.73/ 0.83	0.84/ 0.95	0.92/ 1.05	ns, min
Clock to Out					
Data-Side On-Chip Memory control outputs	T _{PCKCO_DSOCM}	1.58	1.82	1.99	ns, max
Data-Side On-Chip Memory address bus outputs	T _{PCKAO_DSOCM}	1.46	1.68	1.84	ns, max
Data-Side On-Chip Memory data bus outputs	T _{PCKDO_DSOCM}	0.90	1.03	1.13	ns, max

Table 21: PowerPC 405 Instruction-Side On-Chip Memory Switching Characteristics

		Speed Grade			
Description	Symbol	-7	-6	-5	Units
Setup and Hold Relative to Clock (BRAMISOCCLK)					
Instruction-Side On-Chip Memory data bus inputs	T _{PDCK_ISOCM} / T _{PCKD_ISOCM}	0.81/ 0.68	0.93/ 0.78	1.02/ 0.86	ns, min
Clock to Out					
Instruction-Side On-Chip Memory control outputs	T _{PCKCO_ISOCM}	1.33	1.53	1.68	ns, max
Instruction-Side On-Chip Memory address bus outputs	T _{PCKAO_ISOCM}	1.52	1.75	1.92	ns, max
Instruction-Side On-Chip Memory data bus outputs	T _{PCKDO_ISOCM}	1.35	1.55	1.70	ns, max

Table 24: RocketIO X Receiver Switching Characteristics⁽¹⁾

Description	Symbol	Conditions	Min	Typ	Max	Units
Receive total jitter tolerance using default equalization and PRBS-15 pattern	T_{JTOL}	2.488 Gb/s		0.80	0.65	UI ⁽²⁾
		3.125 Gb/s		0.80	0.65	UI
		4.25 Gb/s		0.80	0.65	UI
		6.25 Gb/s		0.80	0.65	UI
Receive random jitter tolerance	$T_{RJ TOL}$	2.488 Gb/s		0.30		UI
		3.125 Gb/s		0.30		UI
		4.25 Gb/s		0.30		UI
		6.25 Gb/s		0.30		UI
Receive sinusoidal jitter tolerance measured at 70 MHz	$T_{SJ TOL}$	2.488 Gb/s		0.30	0.15	UI
		3.125 Gb/s		0.30	0.15	UI
		4.25 Gb/s		0.30	0.15	UI
		6.25 Gb/s		0.30	0.15	UI
Receive deterministic jitter tolerance	$T_{DJ TOL}$	2.488 Gb/s		0.55	0.45	UI
		3.125 Gb/s		0.55	0.45	UI
		4.25 Gb/s		0.55	0.45	UI
		6.25 Gb/s		0.50	0.45	UI
Receive latency ⁽³⁾	T_{RXLAT}			25	34 ⁽⁴⁾	RXUSRCLK cycles
RXUSRCLK duty cycle	T_{RXDC}		45	50	55	%
RXUSRCLK2 duty cycle	T_{RX2DC}		45	50	55	%
Differential receive input sensitivity	V_{EYE}			120	250	mV

Notes:

1. The XC2VPX70 operates at a fixed 4.25 Gb/s baud rate.
2. UI = Unit Interval
3. Receive latency delay RXP/RXN to RXDATA. Refer to [RocketIO X Transceiver User Guide](#) for more information on calculating latency.
4. This maximum may occur when certain conditions are present and clock correction and channel bonding are enabled. If these functions are both disabled, the maximum will be near the typical values.

Input Clock Tolerances

Table 58: Input Clock Tolerances

Description	Symbol	Constraints F _{CLKIN}	Speed Grade						Units
			−7		−6		−5		
			Min	Max	Min	Max	Min	Max	
Input Clock Low/High Pulse Width									
PSCLK	PSCLK_PULSE	< 1MHz	25.00		25.00		25.00		ns
PSCLK and CLKIN ⁽³⁾	PSCLK_PULSE and CLKIN_PULSE	1 – 10 MHz	25.00		25.00		25.00		ns
		10 – 25 MHz	10.00		10.00		10.00		ns
		25 – 50 MHz	5.00		5.00		5.00		ns
		50 – 100 MHz	3.00		3.00		3.00		ns
		100 – 150 MHz	2.40		2.40		2.40		ns
		150 – 200 MHz	2.00		2.00		2.00		ns
		200 – 250 MHz	1.80		1.80		1.80		ns
		250 – 300 MHz	1.50		1.50		1.50		ns
		300 – 350 MHz	1.30		1.30		1.30		ns
		350 – 400 MHz	1.15		1.15		1.15		ns
		> 400 MHz	1.05		1.05		1.05		ns
Input Clock Cycle-Cycle Jitter (Low Frequency Mode)									
CLKIN (using DLL outputs) ⁽¹⁾	CLKIN_CYC_JITT_DLL_LF			±300		±300		±300	ps
CLKIN (using CLKFX outputs) ⁽²⁾	CLKIN_CYC_JITT_FX_LF			±300		±300		±300	ps
Input Clock Cycle-Cycle Jitter (High Frequency Mode)									
CLKIN (using DLL outputs) ⁽¹⁾	CLKIN_CYC_JITT_DLL_HF			±150		±150		±150	ps
CLKIN (using CLKFX outputs) ⁽²⁾	CLKIN_CYC_JITT_FX_HF			±150		±150		±150	ps
Input Clock Period Jitter (Low Frequency Mode)									
CLKIN (using DLL outputs) ⁽¹⁾	CLKIN_PER_JITT_DLL_LF			±1		±1		±1	ns
CLKIN (using CLKFX outputs) ⁽²⁾	CLKIN_PER_JITT_FX_LF			±1		±1		±1	ns
Input Clock Period Jitter (High Frequency Mode)									
CLKIN (using DLL outputs) ⁽¹⁾	CLKIN_PER_JITT_DLL_HF			±1		±1		±1	ns
CLKIN (using CLKFX outputs) ⁽²⁾	CLKIN_PER_JITT_FX_HF			±1		±1		±1	ns
Feedback Clock Path Delay Variation									
CLKFB off-chip feedback	CLKFB_DELAY_VAR_EXT			±1		±1		±1	ns

Notes:

1. "DLL outputs" is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. If both DLL and CLKFX outputs are used, follow the more restrictive specification.
3. If DCM phase shift feature is used and CLKIN frequency > 200 Mhz, CLKIN duty cycle must be within ±5% (45/55 to 55/45).

FG256/FGG256 Fine-Pitch BGA Package Specifications (1.00mm pitch)

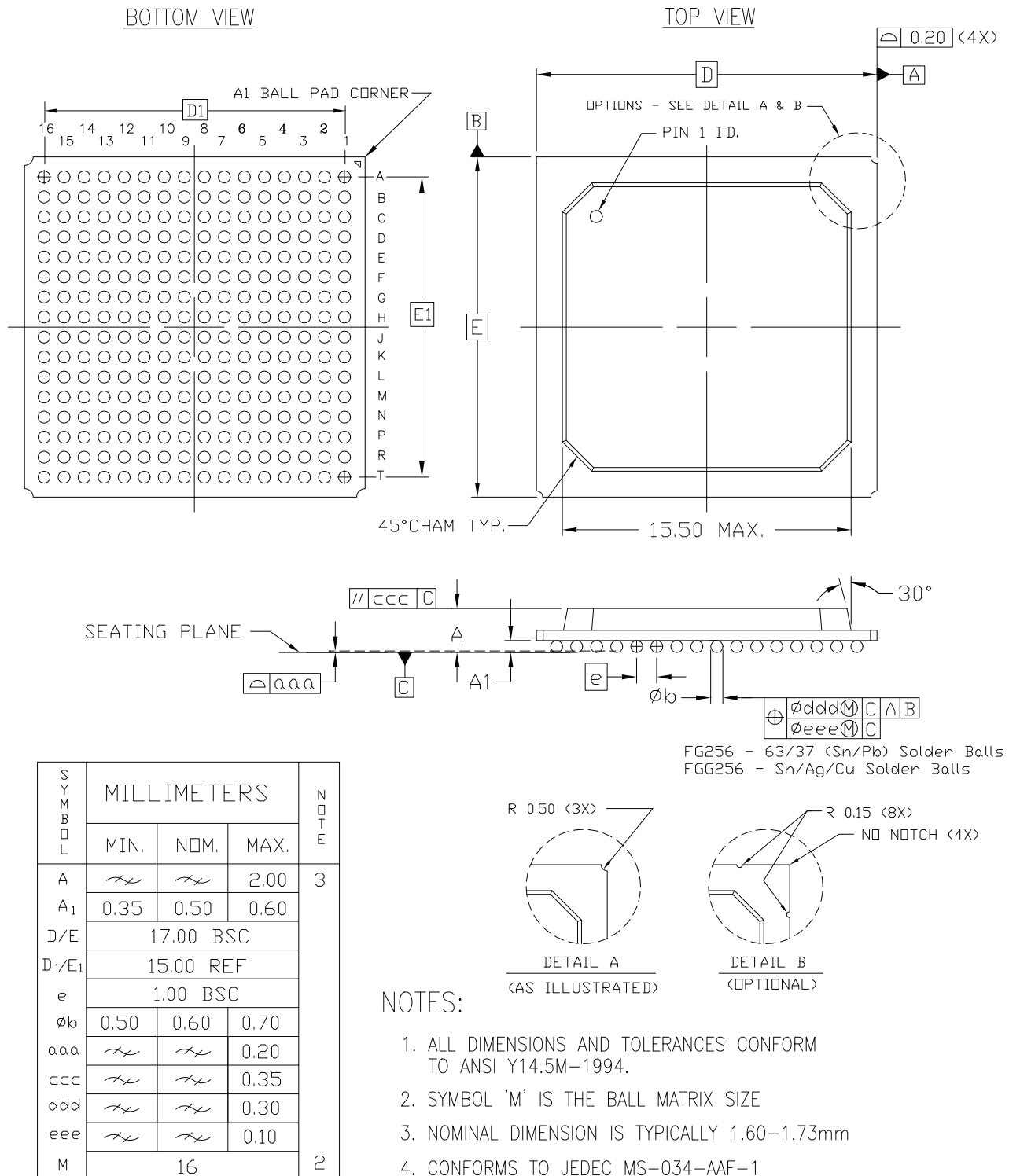


Figure 1: FG256/FGG256 Fine-Pitch BGA Package Specifications

Table 6: FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
2	IO_L56N_2	J21	NC		
2	IO_L56P_2	J22	NC		
2	IO_L58N_2/VREF_2	J18	NC		
2	IO_L58P_2	K18	NC		
2	IO_L60N_2	K19	NC		
2	IO_L60P_2	K20	NC		
2	IO_L85N_2	K21			
2	IO_L85P_2	K22			
2	IO_L86N_2	K17			
2	IO_L86P_2	L17			
2	IO_L88N_2/VREF_2	L18			
2	IO_L88P_2	L19			
2	IO_L90N_2	L20			
2	IO_L90P_2	L21			
3	IO_L90N_3	M21			
3	IO_L90P_3	M20			
3	IO_L89N_3	M19			
3	IO_L89P_3	M18			
3	IO_L87N_3/VREF_3	M17			
3	IO_L87P_3	N17			
3	IO_L85N_3	N22			
3	IO_L85P_3	N21			
3	IO_L60N_3	N20	NC		
3	IO_L60P_3	N19	NC		
3	IO_L59N_3	N18	NC		
3	IO_L59P_3	P18	NC		
3	IO_L57N_3/VREF_3	P22	NC		
3	IO_L57P_3	P21	NC		
3	IO_L55N_3	P20	NC		
3	IO_L55P_3	P19	NC		
3	IO_L54N_3	P17	NC		
3	IO_L54P_3	R18	NC		
3	IO_L53N_3	R22	NC		
3	IO_L53P_3	R21	NC		
3	IO_L51N_3/VREF_3	R20	NC		
3	IO_L51P_3	R19	NC		

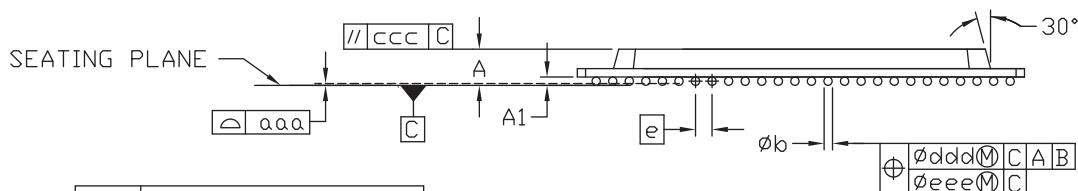
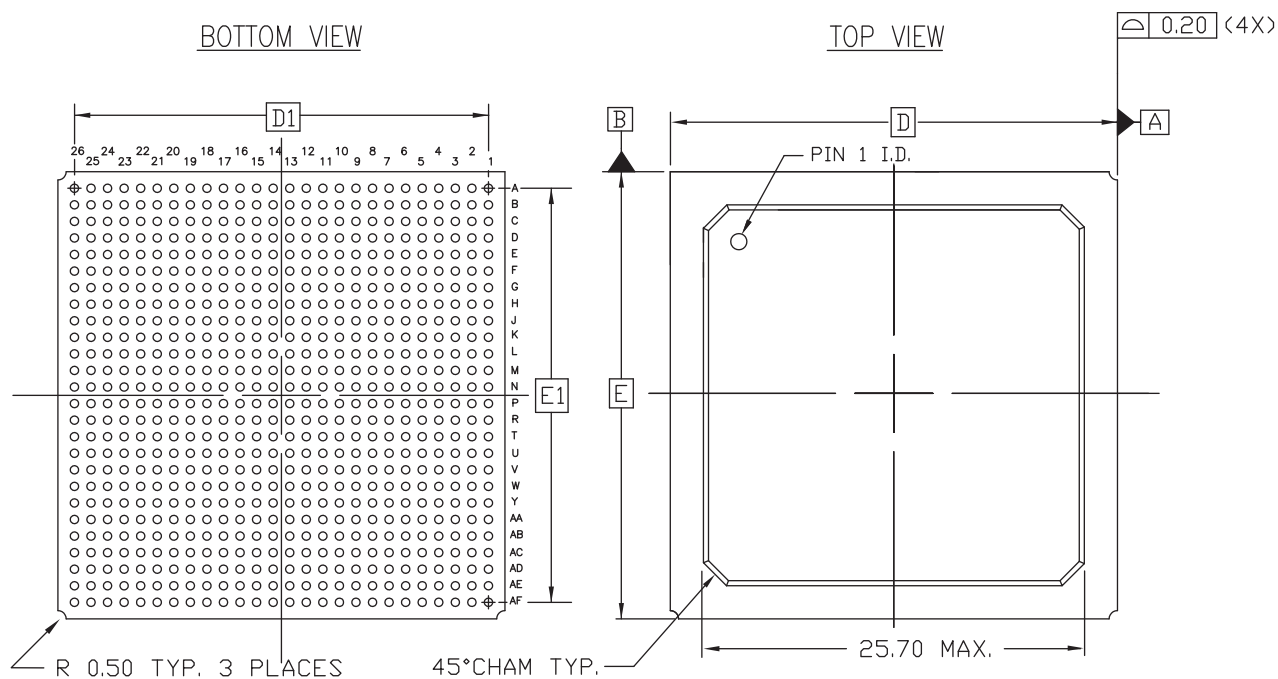
Table 6: FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
6	IO_L06N_6	V1			
6	IO_L43P_6	U4	NC		
6	IO_L43N_6	U3	NC		
6	IO_L45P_6	U2	NC		
6	IO_L45N_6/VREF_6	U1	NC		
6	IO_L47P_6	U5	NC		
6	IO_L47N_6	T5	NC		
6	IO_L48P_6	T4	NC		
6	IO_L48N_6	T3	NC		
6	IO_L49P_6	T2	NC		
6	IO_L49N_6	T1	NC		
6	IO_L51P_6	R4	NC		
6	IO_L51N_6/VREF_6	R3	NC		
6	IO_L53P_6	R2	NC		
6	IO_L53N_6	R1	NC		
6	IO_L54P_6	R5	NC		
6	IO_L54N_6	P6	NC		
6	IO_L55P_6	P4	NC		
6	IO_L55N_6	P3	NC		
6	IO_L57P_6	P2	NC		
6	IO_L57N_6/VREF_6	P1	NC		
6	IO_L59P_6	P5	NC		
6	IO_L59N_6	N5	NC		
6	IO_L60P_6	N4	NC		
6	IO_L60N_6	N3	NC		
6	IO_L85P_6	N2			
6	IO_L85N_6	N1			
6	IO_L87P_6	N6			
6	IO_L87N_6/VREF_6	M6			
6	IO_L89P_6	M5			
6	IO_L89N_6	M4			
6	IO_L90P_6	M3			
6	IO_L90N_6	M2			
7	IO_L90P_7	L2			
7	IO_L90N_7	L3			
7	IO_L88P_7	L4			

Table 7: FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
7	IO_L52P_7	M7			
7	IO_L52N_7/VREF_7	L7			
7	IO_L50P_7	K1			
7	IO_L50N_7	K2			
7	IO_L49P_7	L3			
7	IO_L49N_7	K3			
7	IO_L48P_7	K4			
7	IO_L48N_7	K5			
7	IO_L46P_7	L8			
7	IO_L46N_7/VREF_7	K8			
7	IO_L44P_7	J1			
7	IO_L44N_7	J2			
7	IO_L43P_7	J3			
7	IO_L43N_7	J4			
7	IO_L42P_7	J5			
7	IO_L42N_7	J6			
7	IO_L40P_7	J7			
7	IO_L40N_7/VREF_7	J8			
7	IO_L38P_7	H1			
7	IO_L38N_7	H2			
7	IO_L37P_7	H6			
7	IO_L37N_7	H7			
7	IO_L36P_7	G1			
7	IO_L36N_7	G2			
7	IO_L34P_7	G3			
7	IO_L34N_7/VREF_7	G4			
7	IO_L32P_7	H5			
7	IO_L32N_7	G5			
7	IO_L31P_7	F1			
7	IO_L31N_7	F2			
7	IO_L24P_7	F3	NC		
7	IO_L24N_7	F4	NC		
7	IO_L06P_7	G6			
7	IO_L06N_7	F6			
7	IO_L04P_7	E1			

FG676/FGG676 Fine-Pitch BGA Package Specifications (1.00mm pitch)



FG676 - 63/37 (Sn/Pb) Solder Balls
FGG676 - Sn/Ag/Cu Solder Balls

SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	2.02	2.23	2.44
A ₁	0.40	0.50	0.60
D/E	27.00 BSC		
D ₁ /E ₁	25.00 REF		
e	1.00 BSC		
øb	0.50	0.60	0.70
aaa	\times	\times	0.20
ccc	\times	\times	0.35
ddd	\times	\times	0.30
eee	\times	\times	0.10
M	26		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAL-1

ds083_4_03_053111

Figure 3: FG676/FGG676 Fine-Pitch BGA Package Specifications

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
0	IO_L01N_0/VRP_0		E25			
0	IO_L01P_0/VRN_0		E24			
0	IO_L02N_0		F24			
0	IO_L02P_0		F23			
0	IO_L03N_0		E23			
0	IO_L03P_0/VREF_0		E22			
0	IO_L05_0/No_Pair		G23			
0	IO_L06N_0		H22			
0	IO_L06P_0		G22			
0	IO_L07N_0		F22			
0	IO_L07P_0		F21			
0	IO_L08N_0		D24			
0	IO_L08P_0		C24			
0	IO_L09N_0		H21			
0	IO_L09P_0/VREF_0		G21			
0	IO_L37N_0		E21			
0	IO_L37P_0		D21			
0	IO_L38N_0		D23			
0	IO_L38P_0		C23			
0	IO_L39N_0		H20			
0	IO_L39P_0		G20			
0	IO_L43N_0		E20			
0	IO_L43P_0		D20			
0	IO_L44N_0		B23			
0	IO_L44P_0		A23			
0	IO_L45N_0		H19			
0	IO_L45P_0/VREF_0		G19			
0	IO_L46N_0		E19	NC		
0	IO_L46P_0		E18	NC		
0	IO_L47N_0		C22	NC		
0	IO_L47P_0		B22	NC		
0	IO_L48N_0		F20	NC		
0	IO_L48P_0		F19	NC		
0	IO_L49N_0		G17	NC		
0	IO_L49P_0		F17	NC		
0	IO_L50_0/No_Pair		B21	NC		

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
2	IO_L41N_2		L8	NC		
2	IO_L41P_2		L7	NC		
2	IO_L42N_2		H4	NC		
2	IO_L42P_2		H3	NC		
2	IO_L43N_2		H2			
2	IO_L43P_2		J2			
2	IO_L44N_2		M8			
2	IO_L44P_2		M7			
2	IO_L45N_2		K6			
2	IO_L45P_2		K5			
2	IO_L46N_2/VREF_2		J1			
2	IO_L46P_2		K1			
2	IO_L47N_2		M6			
2	IO_L47P_2		M5			
2	IO_L48N_2		J4			
2	IO_L48P_2		J3			
2	IO_L49N_2		K2			
2	IO_L49P_2		L2			
2	IO_L50N_2		N8			
2	IO_L50P_2		N7			
2	IO_L51N_2		K4			
2	IO_L51P_2		K3			
2	IO_L52N_2/VREF_2		L1			
2	IO_L52P_2		M1			
2	IO_L53N_2		N6			
2	IO_L53P_2		N5			
2	IO_L54N_2		L5			
2	IO_L54P_2		L4			
2	IO_L55N_2		M2			
2	IO_L55P_2		N2			
2	IO_L56N_2		P9			
2	IO_L56P_2		R9			
2	IO_L57N_2		M4			
2	IO_L57P_2		M3			
2	IO_L58N_2/VREF_2		N1			
2	IO_L58P_2		P1			

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
7	VCCO_7	T23				
7	VCCO_7	U23				
N/A	CCLK	AE9				
N/A	PROG_B	J26				
N/A	DONE	AE10				
N/A	M0	AF26				
N/A	M1	AE26				
N/A	M2	AE25				
N/A	TCK	J9				
N/A	TDI	H28				
N/A	TDO	H7				
N/A	TMS	K10				
N/A	PWRDWN_B	AF9				
N/A	HSWAP_EN	K25				
N/A	RSVD	G8				
N/A	VBATT	K9				
N/A	DXP	K26				
N/A	DXN	G27				
N/A	AVCCAUXTX2	B32	NC	NC		
N/A	VTTXPAD2	B33	NC	NC		
N/A	TXNPAD2	A33	NC	NC		
N/A	TXPPAD2	A32	NC	NC		
N/A	GND A2	C30	NC	NC		
N/A	RXPPAD2	A31	NC	NC		
N/A	RXNPAD2	A30	NC	NC		
N/A	VTRXPAD2	B31	NC	NC		
N/A	AVCCAUXRX2	B30	NC	NC		
N/A	AVCCAUXTX4	B28				
N/A	VTTXPAD4	B29				
N/A	TXNPAD4	A29				
N/A	TXPPAD4	A28				
N/A	GND A4	C27				
N/A	RXPPAD4	A27				
N/A	RXNPAD4	A26				
N/A	VTRXPAD4	B27				
N/A	AVCCAUXRX4	B26				
N/A	AVCCAUXTX5	B24	NC	NC	NC	

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
1	IO_L43P_1	B13		
1	IO_L39N_1	G13		
1	IO_L39P_1	F13		
1	IO_L38N_1	J15		
1	IO_L38P_1	J14		
1	IO_L37N_1	B12		
1	IO_L37P_1	A12		
1	IO_L27N_1/VREF_1	D13		
1	IO_L27P_1	D12		
1	IO_L26N_1	L13		
1	IO_L26P_1	K13		
1	IO_L25N_1	F12		
1	IO_L25P_1	E12		
1	IO_L21N_1	B11		
1	IO_L21P_1	A11		
1	IO_L20N_1	K12		
1	IO_L20P_1	J12		
1	IO_L19N_1	C12		
1	IO_L19P_1	C11		
1	IO_L09N_1/VREF_1	F11		
1	IO_L09P_1	E11		
1	IO_L08N_1	H13		
1	IO_L08P_1	H12		
1	IO_L07N_1	G12		
1	IO_L07P_1	G11		
1	IO_L06N_1	B10		
1	IO_L06P_1	A10		
1	IO_L05_1/No_Pair	G10		
1	IO_L03N_1/VREF_1	D10		
1	IO_L03P_1	C10		
1	IO_L02N_1	K11		
1	IO_L02P_1	J11		
1	IO_L01N_1/VRP_1	F10		
1	IO_L01P_1/VRN_1	E10		
2	IO_L01N_2/VRP_2	B8		
2	IO_L01P_2/VRN_2	B9		
2	IO_L02N_2	C9		

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
6	IO_L06N_6	AM34		
6	IO_L07P_6	AN30		
6	IO_L07N_6	AM30		
6	IO_L08P_6	AM26		
6	IO_L08N_6	AL26		
6	IO_L09P_6	AM28		
6	IO_L09N_6/VREF_6	AM29		
6	IO_L10P_6	AL33		
6	IO_L10N_6	AL34		
6	IO_L11P_6	AL27		
6	IO_L11N_6	AK27		
6	IO_L12P_6	AL29		
6	IO_L12N_6	AL30		
6	IO_L13P_6	AL32		
6	IO_L13N_6	AK32		
6	IO_L14P_6	AJ27		
6	IO_L14N_6	AJ28		
6	IO_L15P_6	AL31		
6	IO_L15N_6/VREF_6	AK31		
6	IO_L16P_6	AL28		
6	IO_L16N_6	AK28		
6	IO_L17P_6	AJ26		
6	IO_L17N_6	AH26		
6	IO_L18P_6	AJ33		
6	IO_L18N_6	AJ34		
6	IO_L19P_6	AJ31		
6	IO_L19N_6	AJ32		
6	IO_L20P_6	AG27		
6	IO_L20N_6	AG28		
6	IO_L21P_6	AK29		
6	IO_L21N_6/VREF_6	AJ29		
6	IO_L22P_6	AH33		
6	IO_L22N_6	AH34		
6	IO_L23P_6	AF27		
6	IO_L23N_6	AE27		
6	IO_L24P_6	AJ30		
6	IO_L24N_6	AH30		
6	IO_L25P_6	AH28		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
7	IO_L24N_7	L37		
7	IO_L23P_7	P31		
7	IO_L23N_7	P32		
7	IO_L22P_7	L34		
7	IO_L22N_7/VREF_7	L35		
7	IO_L21P_7	L32		
7	IO_L21N_7	L33		
7	IO_L20P_7	N29		
7	IO_L20N_7	M29		
7	IO_L19P_7	K38		
7	IO_L19N_7	K39		
7	IO_L18P_7	J37		
7	IO_L18N_7	K37		
7	IO_L17P_7	N30		
7	IO_L17N_7	P30		
7	IO_L16P_7	K35		
7	IO_L16N_7/VREF_7	K36		
7	IO_L15P_7	K34		
7	IO_L15N_7	K33		
7	IO_L14P_7	N31		
7	IO_L14N_7	M32		
7	IO_L13P_7	J38		
7	IO_L13N_7	J39		
7	IO_L12P_7	J35		
7	IO_L12N_7	H36		
7	IO_L11P_7	M30		
7	IO_L11N_7	L31		
7	IO_L10P_7	J33		
7	IO_L10N_7/VREF_7	J34		
7	IO_L09P_7	H37		
7	IO_L09N_7	H38		
7	IO_L08P_7	K31		
7	IO_L08N_7	K32		
7	IO_L07P_7	H33		
7	IO_L07N_7	H34		
7	IO_L84P_7	G38	NC	
7	IO_L84N_7	G39	NC	
7	IO_L82P_7	G36	NC	

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
6	IO_L16N_6		AM42		
6	IO_L17P_6		AL33		
6	IO_L17N_6		AL34		
6	IO_L18P_6		AL35		
6	IO_L18N_6		AL36		
6	IO_L19P_6		AL38		
6	IO_L19N_6		AL39		
6	IO_L20P_6		AL31		
6	IO_L20N_6		AL32		
6	IO_L21P_6		AL40		
6	IO_L21N_6/VREF_6		AL41		
6	IO_L22P_6		AK35		
6	IO_L22N_6		AK36		
6	IO_L23P_6		AK33		
6	IO_L23N_6		AK34		
6	IO_L24P_6		AK37		
6	IO_L24N_6		AK38		
6	IO_L25P_6		AK39		
6	IO_L25N_6		AK40		
6	IO_L26P_6		AK31		
6	IO_L26N_6		AK32		
6	IO_L27P_6		AK41		
6	IO_L27N_6/VREF_6		AK42		
6	IO_L28P_6		AJ35		
6	IO_L28N_6		AJ36		
6	IO_L29P_6		AJ33		
6	IO_L29N_6		AJ34		
6	IO_L30P_6		AJ37		
6	IO_L30N_6		AJ38		
6	IO_L31P_6		AJ41		
6	IO_L31N_6		AJ42		
6	IO_L32P_6		AJ31		
6	IO_L32N_6		AJ32		
6	IO_L33P_6		AH33		
6	IO_L33N_6/VREF_6		AH34		
6	IO_L34P_6		AH37		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
0	IO_L34P_0	C30	
0	IO_L35N_0	L29	
0	IO_L35P_0	M29	
0	IO_L36N_0	H28	
0	IO_L36P_0/VREF_0	G29	
0	IO_L76N_0	E29	
0	IO_L76P_0	F29	
0	IO_L77N_0	J29	
0	IO_L77P_0	K29	
0	IO_L78N_0	D28	
0	IO_L78P_0	C29	
0	IO_L79N_0	A29	
0	IO_L79P_0	B29	
0	IO_L80_0/No_Pair	L28	
0	IO_L83_0/No_Pair	M28	
0	IO_L84N_0	G27	
0	IO_L84P_0	G28	
0	IO_L85N_0	E28	
0	IO_L85P_0	F28	
0	IO_L86N_0	J28	
0	IO_L86P_0	K28	
0	IO_L87N_0	C27	
0	IO_L87P_0/VREF_0	C28	
0	IO_L37N_0	A28	
0	IO_L37P_0	B28	
0	IO_L38N_0	L27	
0	IO_L38P_0	M27	
0	IO_L39N_0	H26	
0	IO_L39P_0	H27	
0	IO_L43N_0	E27	
0	IO_L43P_0	F27	
0	IO_L44N_0	J27	
0	IO_L44P_0	K27	
0	IO_L45N_0	D26	
0	IO_L45P_0/VREF_0	D27	
0	IO_L10N_0	A27	NC
0	IO_L10P_0	B27	NC